



RESPONSE UNDER 37CFR1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP # 1731

AF  
JFW

**In The United States Patent And Trademark Office**

Application Number: 10/082,867  
Application Filed: 02/18/2002  
Applicants: Romain L. Billiet et al.  
Title: Ultrasmall Semiconductor Bonding Tools and Method of  
Fabrication Thereof  
Examiner/GAU: Carlos N. Lopez/1731

Penang, Malaysia, Monday, March 6, 2006

DO  
NOT

**AMENDMENT UNDER 37 CFR 1.116**

Mail Stop AF  
Commissioner for Patents  
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Alexandra, VA 22313-1450

Sir:

In response to the Final Office Action mailed on December 7, 2005, applicants request that above application be amended as follows to place it in condition for allowance: